



Solder plus Support

RMA Cored Wire Solder

Rosin Mildly Activated Cored Wire Solder

Features:

- Good Activity Level
 - Good Thermal Transfer
 - Mildly Activated Flux
 - Glycol-Free
 - Good Wetting Properties
- * Meets QQS-571-E Specification and Applicable IPC-J-STD-004 and -006 Requirements

Description:

RMA is a mildly activated, general-purpose wire solder for use in applications requiring good activation. RMA cored wire is active enough for excellent tarnish or oxide removal, and will produce bright shiny solder joints. RMA wire will leave slight to moderate post-process residues that may be left on noncritical applications, but should be removed from any critical applications. RMA cored wire meets Mil-Spec cleanliness requirements without cleaning. IPC flux classification for this material is ROL0.

Availability:

- RMA is standard with a 3.0% flux core for tin-lead (3.0% flux core for lead-free) alloys.
- RMA is available in Sn/Pb, Sn/Pb/Ag, Sn/Ag/Cu, SN100C® alloys.
- Standard spool sizes: ½ lb. for .010 and .015 diameters; 1 lb. for .020, .032, .040, .050, and .062 diameters.
- Packaging of ½ lb. and 1 lb. spools is standard in 12 lb. and 24 lb. cases.
- Other flux percentages, alloys, diameters and spool sizes may be available upon special request.

Application:

- Solder iron tip temperature should be between 340°C-400°C (650°F-750°F) for Sn63, Sn62 and Sn60 alloys, 370°C-425°C (700°F-800°F) for Sn/Ag and Sn/Ag/Cu alloys and 340°C-370°C (650°F-700°F) for Sn43/Pb43/Bi14.
- Hold the solder iron at a 45° to 60° angle to the work surface.
- The solder iron should contact both the component lead and PCB pad surface.
- Solder and flux should flow onto both the lead and pad or lead and barrel to promote optimum flux activity to the joint being worked.
- If additional flux is needed, the use of AIM's RMA202-25 flux is recommended. Operators should use an applicator capable of dispensing precise amounts of flux to eliminate over-saturation and excessive spread.

Cleaning:

If post-process cleaning is desired, is easiest if performed within a two to three hour period post-process. Adequate cleaning may be accomplished using a saponifier. AIMTERGE-520A is recommended. A temperature of 35°C- 65°C (100°-150°F) is sufficient for removing residues. An in-line or other pressurized spray cleaning system is suggested, but is not required.

Handling and Storage:

- RMA cored wire has an indefinite shelf life when proper storage conditions are observed.
- Store RMA in a clean dry area away from moisture and sunlight.
- Do not freeze this product.

Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying MSDS for any specific emergency information.
- Do not dispose of any waste materials in non-approved containers.

Canada +1-514-494-2000 · USA +1-401-463-5605 · Mexico +52-656-630-0032 · Europe +44-1737-222-258

Asia-Pacific +86-755-2993-6487 · India +91-80-41554753 · info@aimsolder.com · www.aimsolder.com

AIM IS ISO9001:2008 & ISO14001:2004 CERTIFIED

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